

SOT960-1

plastic thermal enhanced thin quad flat package; no leads; 60 terminals; body 5.5 x 8.5 x 1.15 mm

8 February 2016

Package information

1. Package summary

Terminal position code	Q (quad)
Package type descriptive code	HTQFN60R
Package type industry code	HTQFN60R
Package style descriptive code	HTQFN (thermal enhanced thin quad flatpack; no leads)
Package style suffix code	R (resin based)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	14-11-2007

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	8.4	-	8.5	8.6	mm
E	package width	5.4	-	5.5	5.6	mm
A	seated height	[tbd]	-	1.15	1.2	mm
A ₂	package height	[tbd]	-	1.15	1.2	mm
n ₂	actual quantity of termination	-	-	60	-	

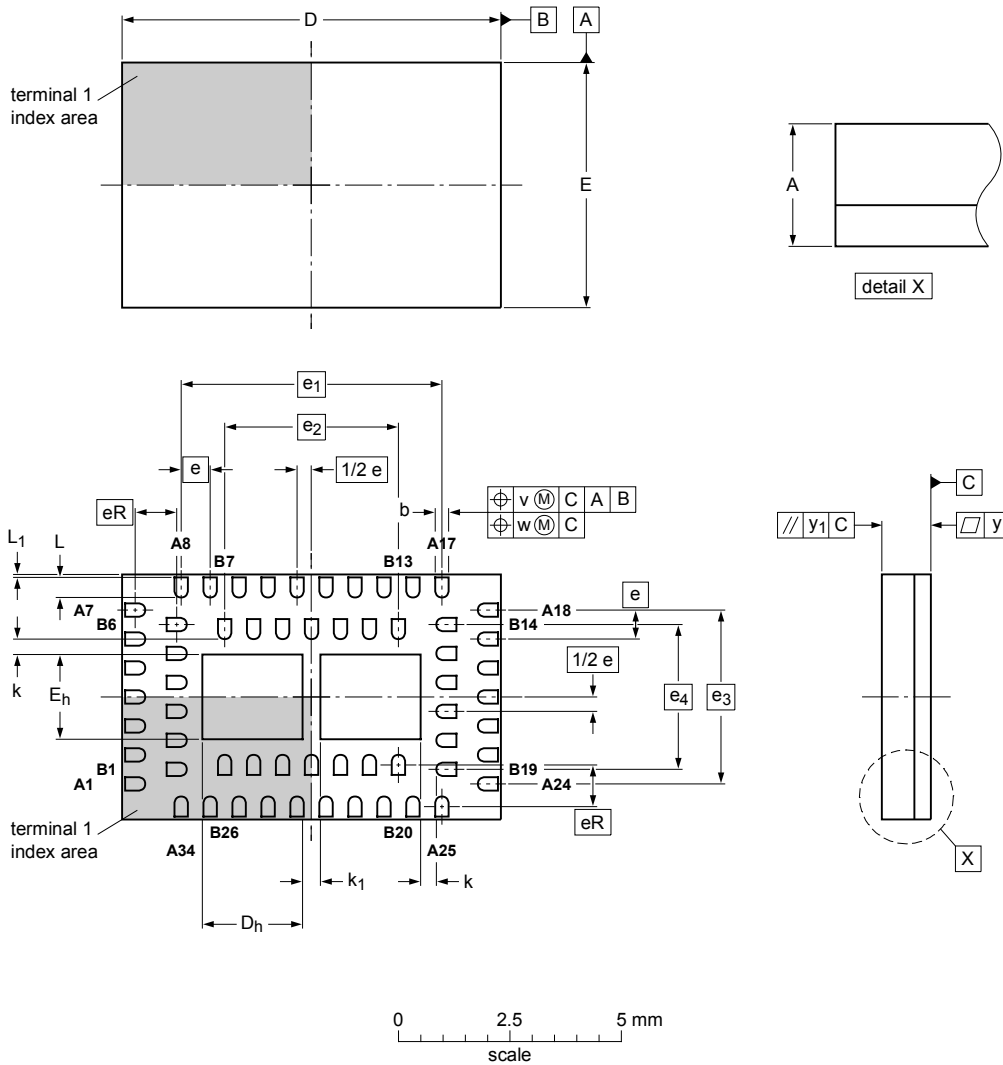


plastic thermal enhanced thin quad flat package;
no leads; 60 terminals; body 5.5 x 8.5 x 1.15 mm

2. Package outline

HTQFN60R: plastic thermal enhanced thin quad flat package; no leads;
60 terminals; resin based; body 5.5 x 8.5 x 1.15 mm

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DIMENSIONS (mm are the original dimensions)

UNIT	A _{max}	b	D	D _h	E	E _h	e	e ₁	e ₂	e ₃	e ₄	e _R	k	k ₁	L	L ₁	v	w	y	y ₁
mm	1.2	0.32 0.28	8.6 8.4	2.35 2.15	5.6 5.4	2.0 1.8	0.65	5.85	3.9	3.9	3.25	0.95	0.4 0.3	0.45 0.35	0.48 0.43	0.1 0.0	0.1	0.05	0.05	0.1

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT960-1	---	---	---			06-08-02 07-11-14

Fig. 1. Package outline HTQFN60R (SOT960-1)

plastic thermal enhanced thin quad flat package;
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3. Legal information

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